



Material Content Data Sheet



Sales Product Name				BSC014N03MS G		Issued		4. July 2019	
MA#				MA005345246					
Package				PG-TDSON-8-7		Weight*		119.20 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.396	1.17	1.17	11711	11711	
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		95		
	non noble metal	iron	7439-89-6	0.038	0.03		317		
wire	non noble metal	copper	7440-50-8	37.762	31.68	31.72	316802	317214	
	noble metal	gold	7440-57-5	0.045	0.04	0.04	375	375	
encapsulation	organic material	carbon black	1333-86-4	0.085	0.07		717		
	plastics	epoxy resin	-	6.750	5.66		56631		
leadfinish	inorganic material	silicondioxide	60676-86-0	35.887	30.11	35.84	301077	358425	
	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12179	12179	
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1389	1389	
solder	non noble metal	tin	7440-31-5	0.039	0.03		327		
	noble metal	silver	7440-22-4	0.049	0.04		409		
heat sink clip	non noble metal	lead	7439-92-1	1.862	1.56	1.63	15618	16354	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		56		
heatspreader	non noble metal	iron	7439-89-6	0.022	0.02		187		
	non noble metal	copper	7440-50-8	22.292	18.70	18.73	187016	187259	
heatspreader	inorganic material	phosphorus	7723-14-0	0.003	0.00		29		
	non noble metal	iron	7439-89-6	0.011	0.01		95		
*deviation	non noble metal	copper	7440-50-8	11.320	9.50	9.51	94970	95094	
						Sum in total:		100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com